

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)

5. (Previously Presented) The semiconductor device as set forth in claim 19,
wherein:

said spacer is an adhesive tape or an adhesive agent.

6. (Previously Presented) The semiconductor device as set forth in claim 16,
wherein:

said flexible substrate is made of polyimide series resin, and is formed in thickness
of not more than 40 μm .

7. (Cancelled)
8. (Cancelled)
9. (Cancelled)
10. (Cancelled)
11. (Cancelled)
12. (Cancelled)
13. (Cancelled)
14. (Cancelled)
15. (Cancelled)

16. (Previously Presented) A semiconductor device, comprising:
a film-like flexible substrate having a wiring pattern formed on a front surface thereof;
external connection terminals formed at both end portions of said flexible substrate; and
a semiconductor element mounted on the front surface of said flexible substrate, wherein at least one end portion of said flexible substrate is folded almost in contact with a back surface of said flexible substrate, so that a flat portion is formed at said at least one end portion, the flat portion having the external connection terminals.

17. (Previously Presented) A semiconductor device, comprising:
a film-like flexible substrate having a wiring pattern formed on a front surface thereof;
external connection terminals formed at both end portions of said flexible substrate; and
a semiconductor element mounted on the front surface of said flexible substrate, wherein at least one end portion of said flexible substrate is folded almost in contact with a back surface of said flexible substrate, so that a flat portion is formed at said at least one end portion, and the flat portion has the external connection terminals which are connectible to a member to be connected provided over the front surface of said flexible substrate.

18. (Previously Presented) A semiconductor device, comprising:
a film-like flexible substrate having a wiring pattern formed on a front surface thereof;
external connection terminals formed at both end portions of said flexible substrate; and
a semiconductor element mounted on the front surface of said flexible substrate,

wherein both end portions of said flexible substrate are folded almost in contact with a back surface of said flexible substrate, so that flat portions are formed at the respective end portions, each of the flat portions having the external connection terminals, and the external connection terminals at one flat portion are connected to a member to be connected provided below said flexible substrate, while the external connection terminals at the other flat portion are connected to a printed wiring substrate below said flexible substrate.

19. (Previously Presented) The semiconductor device as set forth in claim 16, further comprising:

a spacer for fixing the flat portion to the back surface of said flexible substrate.

20. (Currently Amended) A semiconductor device, comprising:

a wiring pattern formed on a front surface of a film-like flexible substrate; and
a semiconductor element and external connection terminals which are connected to the wiring pattern,

wherein at least one end portion of said flexible substrate is folded almost in contact with ~~said a~~ a back surface of said flexible substrate, so that a flat portion is formed at said at least one end portion, the flat portion having the external connection terminals.

21. (Currently Amended) A semiconductor device comprising:

a wiring pattern formed on a film-like flexible substrate;
a semiconductor element and an external connection terminal being provided on a front surface of the film-like flexible substrate and electrically connected by the wiring pattern;

the external connection terminal being provided at ~~a~~ an end portion of the film-like flexible substrate, the end portion of the film-like flexible substrate at which the external connection terminal is situated being folded back toward a back surface of the film-like

flexible substrate and almost in contact with the back surface so that the external connection terminal has an orientation for contact with an electrode of a liquid crystal display substrate.

22. (Previously Presented) The semiconductor device as set forth in claim 16, wherein in the end portion, only the flat portion has the external connection terminals.